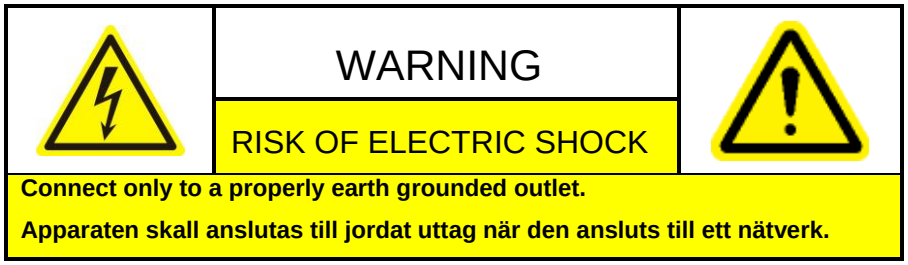
IMPORTANT SAFETY & REGULATORY INFORMATION

SAFETY WARNINGS and CAUTIONS

The Intel® Xeon Phi™ coprocessor board shall only be installed into a host system that is Listed, Certified, or Approved in compliance with safety and electromagnetic compatibility regulations in the location of operation

Refer to the host system user documentation for safety, regulatory and installation instructions for the system.

Prior to installation or removal of the Intel® Xeon Phi™ coprocessor board turn off the host system power and disconnect the host system mains plug from the socket outlet to ensure all power is off.

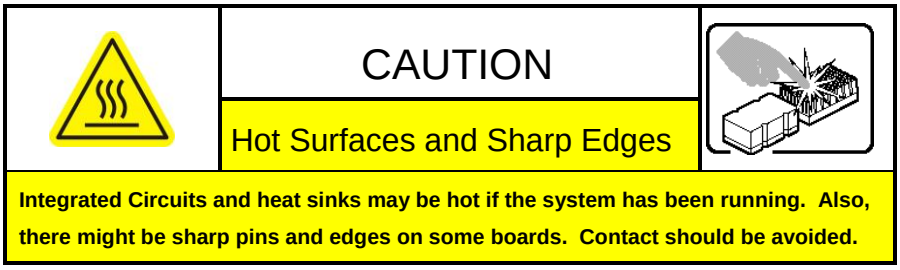


System Grounding (Earthing): To avoid shock, ensure that Protective Earth (grounding) is maintained, the host system, powered peripherals and monitors must be connected to properly wired and earthed (grounded) socket outlets.

Power Connect and Disconnect: The mains (AC power) supply cord for the host system is the primary disconnect device for mains (AC power), disconnect the mains cord from the socket outlet to remove all DC power from the device. The socket outlet shall be installed near the equipment and shall be readily accessible.

Do not connect or disconnect any cables or perform installation or maintenance of this product during an electrical storm.

Cooling Requirements: Leave a minimum clearance area of 5 centimeters (2 inches) at the rear panel for cooling purposes. Refer to the Intel® Xeon Phi™ Coprocessor Data Sheet for additional information on air flow, Thermal Design Power and maximum ambient temperatures.



Thermal and Mechanical Injury: Certain components such as heat sinks, power regulators, and processors may be hot; when servicing the host system or this device care should be taken to avoid these components

Host system enclosure covers: To ensure proper cooling, to protect internal components and to reduce risk of injury install and secure all host system covers prior to operation of the system.

Electrostatic Discharge Warning: To avoid damage to the components on this board observe ESD precautions for handling. During servicing this board must be on a properly grounded ESD dissipative surface. A properly grounded ESD wrist strap must be worn during installation of the board or connection of cables.

Electro Magnetic Interference: NOTE: This equipment has been tested in a typical host system and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation.
This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:
—Reorient or relocate the receiving antenna.
—Increase the separation between the equipment and receiver.
—Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
—Consult the dealer or an experienced radio/ TV technician for help.

Industry Canada: This Class B digital apparatus complies with Canadian Standard ICES-003.
Cet appareil numerique de la classe B est conform a la norme NMB-003 du Canada.

For additional information on the installation and operation of this device refer to the documentation located at: http://www.intel.com/content/www/us/en/processors/xeon/xeon-phi-coprocessor-datasheet.html (this link will be live November 12, 2012, prior to that date contact your Intel customer representative for this information.)

For Models SE10X and 71S1P the following conditions of acceptability apply:

The following end-product enclosures are required: Fire, Electrical (the last 5.5 mm of the board may be accessible in the end product.)

As model 71S1P may have different airflow depending on the shape and presence of a rear plate in the end-product, and the cooling solution for model 7110X is to be supplied in the end-product, the heating test shall be repeated during end-product evaluation.